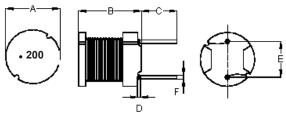
# Inductor Radial Leaded

## multicomp PRO





### **Configurations and Dimensions**



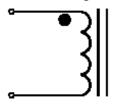
**Top View** 

**Front View** 

**Bottom View** 

Note: White dot of marking indicates the start terminal of winding

#### **Schematic Diagram**



Note:

- 1. Wire UEFN/U (155°C) Ø0.5mm
- 2. 25.5TS (Reference) C.W

### **Test Data for Mechanical**

Test Item	A mm	B mm	C mm	D mm	E mm	F mm
Specification	7.8 ±0.5	9.5 ±0.5	5 ±1	2 (Max.)	5 ±0.5	Ø0.7 (Ref.)
1	7.77	9.25	5.31	1.2	5.21	0.67
2	7.78	9.25	5.27	1.34	5.17	0.68
3	7.77	9.27	5.38	1.47	5.11	0.67
4	7.79	9.3	5.26	1.39	5.2	0.69
5	7.8	9.29	5.17	1.21	5.21	0.7
Average	7.78	9.27	5.28	1.32	5.18	0.68

### **Electrical Characteristics**

Test Condition		
1kHz 0.25V	L	20μH ±10%
T <sub>A</sub> = 25°C	DCR	50mΩ (Max)
1kHz 0.25 V Irms = 2.2A	ΔΤ	Temperature rise 40°C (Max.)

Operating temperature : -55°C to +130°C

### **Material List**

No.	Item	Material Description
1	Core	F4F DR2W7.8 × 9.5 (SW) RCH B3.6 F5.4 P5
2	Wire	Ø0.5mm UEFN/U (155°C)
3	Solder (Lead-free)	Sn99.3% / Cu0.7%

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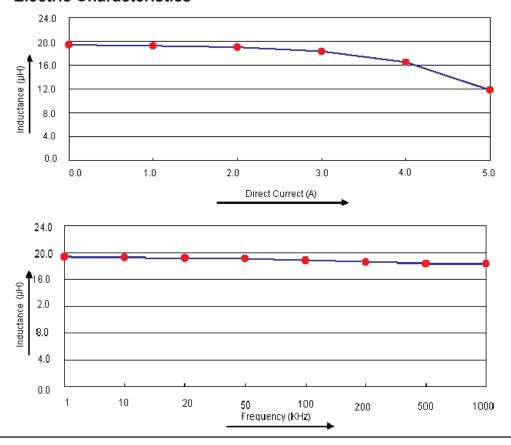
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### **Reliability Test**

Test Item	Specifications		Test Me	Test Method and Remarks		
Operating temperature range	-55°C to +130°C		Including temperature r	ise due to self-generated heat.		
Storage condition	Ambient temperature : 0°C to 40°C Humidity : Below 70% RH		To maintain the solderability of terminal electrodes, care must be taken to control temperature and humidity in the storage area.			
Moisture sensitivity	Appearance  DCR change Inductance change	: No abnormality No damage : Within ±5% : Within ±5%	According to J-STD-02 Test condition Test duration Recovery	OB level 3 : 60°C 60% RH : 40 hrs : 1 to 2 hours of recovery under the standard condition after the removal from the test chamber.		
Solderability	All termination shall exhibit a continuous solder coating free from defects for a minimum of 95% of the surface area of any individual lead.		According to J-STD-00. Steam aging category Steam aging duration Solder Solder temperature Dip time	: 97°C 98% RH		

### **Electric Characteristics**



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# Inductor Radial Leaded



#### **Test Data for Electrical**

Test Item	L µH	DCR Ω	ΔΤ
Condition	1kHz 0.25V	at 25°C	1kHz 0.25V Irms = 2.2A
Specification	20 ±10%	50 (Max.)	Temperature rise 40°C (Max.)
1	19.3	39.46	
2	19.52	39.18	
3	19.3	39.35	OK
4	19.42	39.01	
5	19.44	39.23	
Average	19.4	39.25	OK

### **Part Number Table**

Description	Part Number	
Inductor, 20µH, 10%, Radial Leaded	MCSCH895-200KU	

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